

#### Silicon Carbide Schottky Barrier Rectifier diode in bare die form

### Rev 1.0 30/10/23

### Features:

- Capable of high temperature operation >= 175°C
- High Frequency Operation
- High Surge Current Capability
- No Reverse Recovery / No Forward Recovery
- Positive Temperature Coefficient

## Ordering Information:

The following part suffixes apply:

- No suffix MIL-STD-750 /2073 Visual Inspection
- "H" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2073 Visual Inspection + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

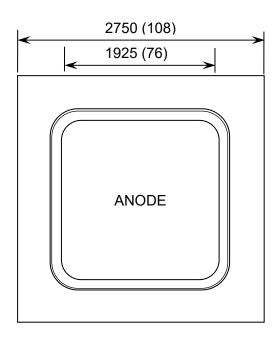
For further information on LAT process flows see below.

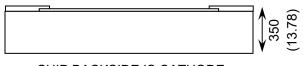
www.siliconsupplies.com\quality\bare-die-lot-qualification

# Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection By specific request

## Die Dimensions in µm (mils)





CHIP BACKSIDE IS CATHODE

# Mechanical Specification

Die Size (Unsawn)	2750 x 2750 108 x 108	µm mils	
Anode Pad Size	1925 x 1925 76 x 76	µm mils	
Die Thickness	350 (±20) 13.78 (0.79)	µm mils	
Top Metal Composition	Al 4µm		
Back Metal Composition	Ag 0.4µm		





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Absolute Maximum R	Ratings $T_J = 25^{\circ}C$ unless otherwise stated
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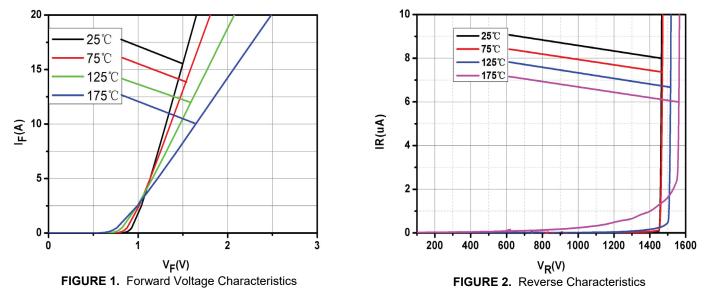
PARAMETER	SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage	V <sub>RRM</sub>	1200	V
Surge peak reverse voltage	V <sub>RSM</sub>	1200	V
DC Peak Blocking Voltage	V <sub>BR</sub>	1200	V
Average forward rectified current	I <sub>F(AV)</sub>	15	А
Repetitive Peak Forward Surge Current	I <sub>FRM</sub>	68	А
Peak Single-Cycle Non-Repetitive Surge Current	I <sub>FSM</sub>	130	A
Operating Junction temperature	TJ	-55 to 175	C°
Storage Temperature Range	T <sub>STG</sub>	-65 to 175	°C

### Electrical Characteristics T<sub>J</sub> = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Maximum instantaneous forward voltage <sup>1</sup>	V <sub>F1</sub>	V <sub>RRM</sub> =1200V, I <sub>FM</sub> = 15A	-	1.50	1.80	V
	V <sub>F2</sub>	V <sub>RRM</sub> = 1200V, I <sub>FM</sub> = 15A, T <sub>J</sub> = 175°C	-	2.20	3.00	
Maximum reverse leakage current <sup>1</sup>	I <sub>RM</sub> @ V <sub>RM</sub>	V <sub>R</sub> = 1200V	-	3	40	μΑ
		V <sub>R</sub> = 1200V, T <sub>J</sub> = 175°C	-	10	50	
Junction Capacitance	CT	V <sub>R</sub> = 0V, f = 1MHz,	-	990	-	pF
Reverse Recovery Charge	Qc	V <sub>R</sub> = 800V , I <sub>F</sub> = 15A, di/dt = 200A/µs	-	76.32	-	nC
Capacitance Stored Energy	Ec	V <sub>R</sub> = 800V	-	39.24	-	μJ

**1.** Pulse Width≤  $300\mu$ s, Duty Cycle ≤ 2.0%

### Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise stated







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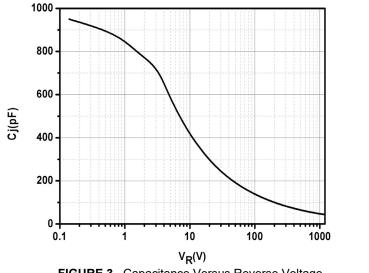


FIGURE 3. Capacitance Versus Reverse Voltage

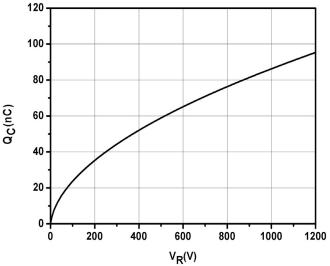


FIGURE 4. Total Capacitance Charge Versus Reverse Voltage

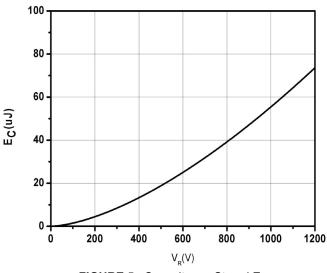


FIGURE 5. Capacitance Stored Energy

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